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COOL-BOND

CB7208-A

In situ "Curing"
Pressure Sensitive
Electrically Insulating
Film Adhesive

IDEAL FOR:

- Component Attach**
- Heat Sink Attach**
- Substrate Attach**

DESCRIPTION:

CB7208-A is a modified version of TP7208-EDA designed to have improved bond strength at ambient and elevated temperature immediately upon attachment. CB7208-A is an aluminum nitride filled, medium bond strength, "pressure-sensitive" instant-bonding thermally conductive film adhesive. It is designed for bonding heat sinks, component, and substrate.

CB7208-A provides >200 psi die-shear bond strength and >30 psi pull strength instantly upon attachment at ambient. The bond strength will improve to >600 psi in-situ over time when temperature exceeds 80C.

AVAILABILITY:

CB7208-A is available in sheet sizes or as custom preforms. Standard thicknesses are 0.006" and 0.010". Special thicknesses are available.

APPLICATION PROCEDURES:

- (1) Keep product at room temperature for 15 minutes before using.
- (2) Before using, remove one side of release liner from adhesive. Cut to desired size.
- (3) Place on substrate or component with rolling finger pressure, then remove the other release liner.
- (4) Place component on substrate with insertion pressure of 10 psi or more. More bond strength will develop in-situ over time during operation.

TYPICAL PROPERTIES*

Electrical Resistivity (25°C/ 1s Place)	>1x10 ¹⁴ ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	-25
Lap-Shear Strength	>200 psi >1.4 N/mm ²
Device Push-off Strength	>600 psi >4.1 N/mm ²
Hardness (Type)	<40 (A)
Cured Density (gm/cc)	2.2
Thermal Conductivity	25 Btu-in/hr-ft ² -°F 3.6 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	110
Maximum Continuous Operation Temp. (°C)	150

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

After 30 min. @80C

Temperature	Time	Pressure
	Bond Force	
25°C	>600 psi	
50°C	>500 psi	
75°C	>300 psi	
100°C	>200 psi	
125°C	>150 psi	

SHELF LIFE:

Storage temperature	Shelf Life
0-5°C	1 yr
	in sealed package

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to MSDS for more details.

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